

42390.P13267



#6/Response
(NE)
PATENT
2/12/03
RECEIVED
FEB 11 2003
TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Sambasivam, et al.

Serial No.: 10/033,854

Filed: December 19, 2001

For: UNDERFILL MATERIALS
DISPENSED IN A FLIP CHIP
PACKAGE BY WAY OF A
THROUGH HOLE

Examiner: Khiem Nguyen

Group Art Unit: 2823

Attorney Docket No.: 42390.P13267

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(u)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

1/31/03
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)
DEBORAH L. HIGMAN
Typed/printed name of person whose signature is contained above

RESPONSE AFTER FINAL REJECTION

Box AF
Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed December 3, 2002, please consider the following remarks: